



Product Change Notification / NTDO-15KTCA141

Date:

07-Sep-2021

Product Category:

USB Products

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4572.003 Final Notice: Qualification of MTAI as an additional assembly site for selected USB4715, USB4914 and USB4925 device families available in 48L VQFN (7x7x1 mm) package.

Affected CPNs:

[NTDO-15KTCA141_Affected_CPN_09072021.pdf](#)
[NTDO-15KTCA141_Affected_CPN_09072021.csv](#)

Notification Text:

PCN Status:Final notification.

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:Qualification of MTAI as an additional assembly site for selected USB4715, USB4914 and USB4925 device families available in 48L VQFN (7x7x1 mm) package.

Pre and Post Change Summary:

For CPNs USB4925-I/Y9XVAA, USB4925T-I/Y9XVAA and USB4914T-I/Y9XVBA:

	Pre Change		Post Change		
Assembly Location	Amkor Assembly & Test (Shanghai) Co., LTD (ANAC)	ASE Inc. - Kaoshiung (ASE)	Amkor Assembly & Test (Shanghai) Co., LTD (ANAC)	ASE Inc. - Kaoshiung (ASE)	Microchip Technology Thailand(HQ) (MTAI)
Wire material	CuPdAu	CuPdAu	CuPdAu	CuPdAu	CuPdAu
Die attach material	CRM1085A	EN-4900F	CRM1085A	EN-4900F	3280
Molding compound material	G631BQF	G631H	G631BQF	G631H	G700LTD
Lead frame material	C194	C194	C194	C194	C194
DAP Surface Prep	Ag ring plated on DAP	Ag ring plated on DAP	Ag ring plated on DAP	Ag ring plated on DAP	Ag ring plated on DAP
Lead frame design	Please see attached pre and post change comparison.				

For CPNs USB4715/Y9X, USB4715-I/Y9X, USB4715-I/Y9XVAA, USB4914-I/Y9XVAA, USB4914-I/Y9XVBA, USB4715T/Y9X, USB4715T-I/Y9X, USB4715T-I/Y9XVAA and USB4914T-I/Y9XVAA:

	Pre Change		Post Change	
Assembly Location	ASE Inc. - Kaoshiung (ASE)		ASE Inc. - Kaoshiung (ASE)	Microchip Technology Thailand(HQ) (MTAI)
Wire material	CuPdAu		CuPdAu	CuPdAu
Die attach material	EN-4900F		EN-4900F	3280
Molding compound material	G631H		G631H	G700LTD
Lead frame material	C194		C194	C194
DAP Surface Prep	Ag ring plated on DAP		Ag ring plated on DAP	Ag ring plated on DAP
Lead frame design	Please see attached pre and post change comparison.			

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve manufacturability by qualifying MTAI as an additional assembly site.

Change Implementation Status:In Progress

Estimated First Ship Date:

September 10, 2021 (date code: 2137)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	September 2021			
Workweek	37	38	39	40
Qual Report Availability	X			

Final PCN Issue Date	X			
Estimated Implementation Date	X			

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

September 07, 2021: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_NTDO-15KTCA141_Pre_and_Post_Change_Summary.pdf](#)

[PCN NTDO-15KTCA141_Qual Report.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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